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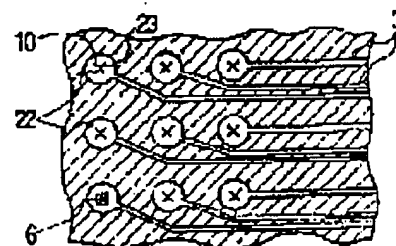
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(54) CONTACT FILM FOR SEMICONDUCTOR INTEGRATED CIRCUIT ELEMENT TEST

(57)Abstract:

PURPOSE: To provide a contact film for semiconductor integrated circuit element test which ensures electrical contact between a terminal of semiconductor integrated circuit element and a terminal through hole of the contact film.

CONSTITUTION: A conductive land 22 which is arranged corresponding to a terminal 6 of a semiconductor integrated circuit element and has a terminal through hole 10 including a cut-groove to which the terminal 6 is inserted is provided on a film. Therefore, the terminal 6 of the semiconductor integrated circuit element is surely placed electrically in contact with the land 22, resulting in highly reliable electrical characteristic test.



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